

- Glass passivated chip junction
- Ideal for printed circuit boards
- High surge current capability
- Solder dip 275 °C max. 7 s, per JESD 22-B106



General purpose use in AC/DC bridge full wave rectification for monitor, TV, printer, power supply, switching mode power supply, adapter, audio equipment, and home appliances applications.

Mechanical Data

• Package: GBU

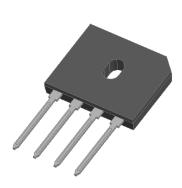
Molding compound meets UL 94 V-0 flammability

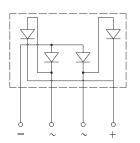
rating, RoHS-compliant

• Terminals: Tin plated leads, solderable per

J-STD-002 and JESD22-B102

• Polarity: As marked on body





■Maximum Ratings (Ta=25°C Unless otherwise specified)

■ Maximum Ratings (1a-23 € Offices otherwise specified)					
PARAMETER		SYMBOL	UNIT	GBU816	
Device marking code				GBU816	
Maximum Repetitive Peak Reverse Voltage		V_{RRM}	V	1600	
Maximum RMS Voltage		V _{RMS}	V	1120	
Maximum DC blocking Voltage		V _{DC}	V	1600	
Average rectified output current	With heatsink Tc =115°C	I _O	А	8	
@60Hz sine wave, R-load	Without heatsink Ta =25°C			2.5	
Forward Surge Current (Non-repetitive) @60Hz Half-sine wave,1 cycle, Tj=25°C Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, Tj=25°C		I _{FSM}	А	160	
				320	
Current squared time @1ms≤t≤8.3ms Tj=25°C, Rating of per diode		l ² t	A ² S	106	
7Storage temperature		Tstg	°C	-55 ~ +150	
Junction temperature		Tj	°C	-55 ~ + 150	
Dielectric strength @ Terminals to case, AC 1 minute		Vdis	KV	2.5	
Mounting torque @Recommend torque: 5kg·cm		Tor	kg∙ cm	8	



GBU816

■Electrical Characteristics (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	GBU816
Maximum instantaneous forward voltage drop per diode	V _F	٧	I _{FM} =4.0A	1.1
Maximum DC reverse current at rated	I _R	μΑ	Tj =25°C	5
DC blocking voltage per diode			Tj =125℃	100
Typical junction capacitance			Measured at 1MHz and Applied Reverse Voltage of 4.0 V.D.C	42

■Thermal Characteristics $(T_a=25$ $^{\circ}$ C Unless otherwise specified)

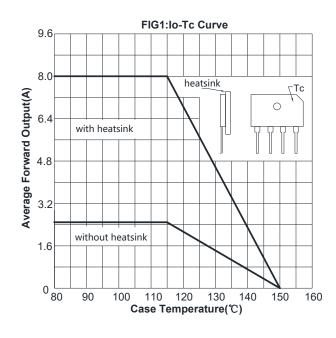
PARAMETER		SYMBOL	UNIT	GBU816
Thermal Resistance	Between junction and ambient, Without heatsink	R _{0J-A}	°C/W	25
	Between junction and case, With heatsink	$R_{ heta J-C}$	C/VV	2

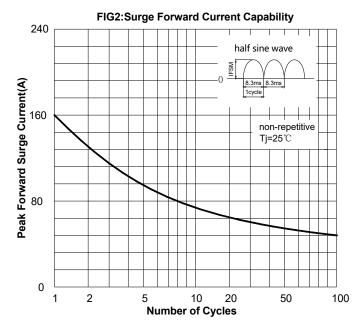
Note: Device mounted on 75mm x 45mm x 5.5mm Aluminum Plate Heatsink.

■Ordering Information (Example)

PREFERED P/N	PACKING CODE	UNIT WEIGHT(g)	MINIIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
GBU816	B1	Approximate 3.96	20	1000	2000	TUBE

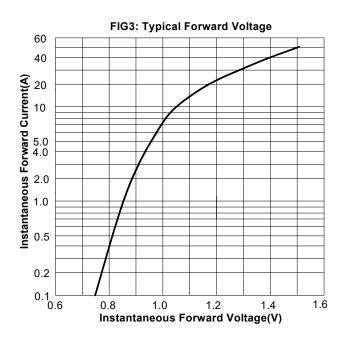
■ Characteristics (Typical)

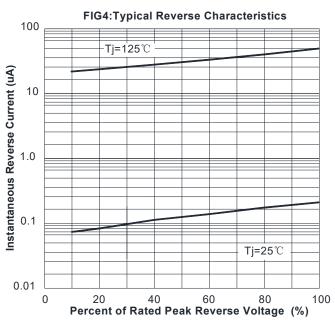




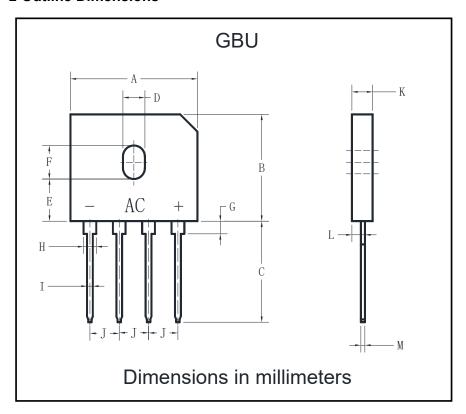








■ Outline Dimensions



Dim	Min	Max	
Α	21.80	22.30	
В	18.30	18.80	
С	17.50	18.00	
D	3.30	3.90	
Е	7.10	7.50	
F	5.50	5.90	
G	1.91	2.54	
Н	2.06	2.54	
I	1.02	1.27	
J	4.83	5.33	
K	3.30	3.56	
L	2.40	2.66	
М	0.46	0.56	



GBU816

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